



DISCRIPTION

FEATURES

Ceramic Core
 High frequency design
 Excellent Q values
 Excellent SRF
 High reliability
 Excellent thermal stability

OPTIONS

Tape & Reel is Standard (Qty: 3.000 Pcs)
 Bulk Packing Available for smaller quantities
 Tolerance: J = 5% and K=10% is Standard,
 tighter Tolerance available (MOQ on request)

APPLICATIONS

Modems
 Mobile Radios
 Cordless Telephones
 Global Positioning Systems
 Telecommunications Systems

PHYSICAL CHARACTERISTICS

- Testing : (Equivalents acceptable) Inductance & Q-HP4191A + HP4291A
 SRF : HP8553B ; RDC : 25°C
- Operating Temperature : Ceramic -55°C ~ 125°C
- Pad metalization : Tungsten-nickel with gold flash
- Solder methods : Wave, Reflow, Vapor Phase
- Solderability : Max 260°C for 10 seconds
- Marking : EIA color code

ELECTRICAL SPECIFICATIONS

Properties	Test conditions		Value	Unit	Tol.
Inductance		L	3,9	nH	see Site 2
Q factor		Q	50		min.
DC-resistance		DCR typ.	---	Ω	typ.
DC-resistance		DCR max.	0,035	Ω	max.
Self-Res. Freq.		SRF	6000	Mhz	min.
Test-Freq.			1500	Mhz	
Rated Current		IDC	1000	mA	max.
Saturation Current		Isat	---	mA	typ.

1. This electronic component is meant to be used in general electronic equipment. Before the incorporation of this component into any equipment with higher and more reliable requirements such as aviation, aerospace, submarine, nuclear control, transportation, transportation signal, disaster prevention, medical, public information network, etc. or if there is a possibility of injuries or damages to the human body, Edcon -Components must be informed before the stage of design-in. Evaluation checks for safety have to be performed on each electronic components used in electrical circuits that require high safety and reliability functions.

SMT WIRE-WOUND CERAMIC CHIP INDUCTORS

Part No.: **S12004-3N9**

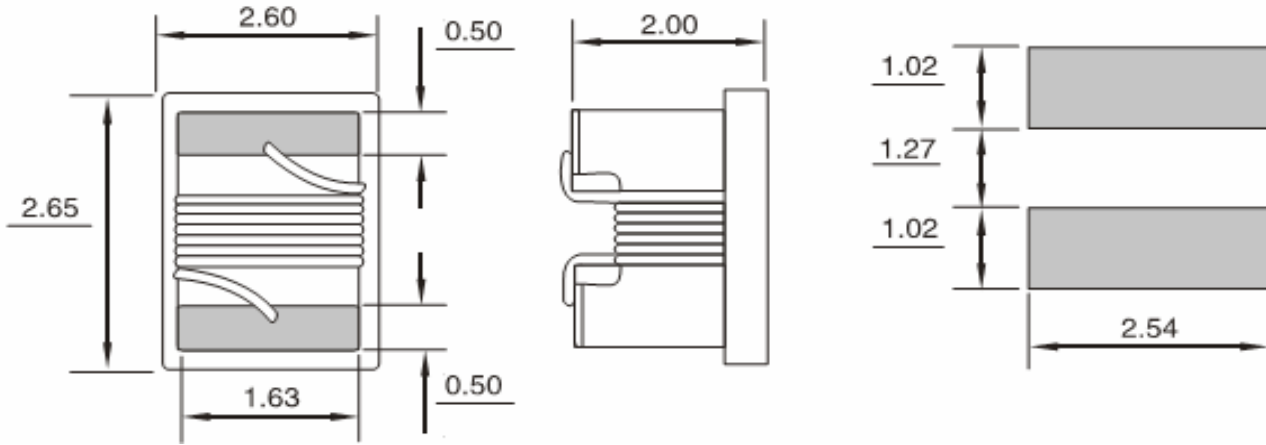
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TECHNICAL INFORMATIONS

Dimensions (mm)

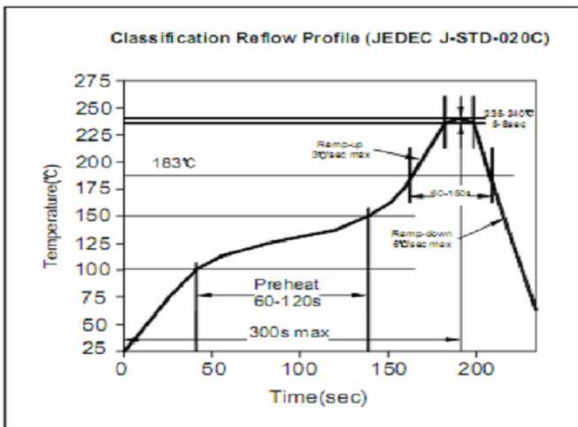


Ordering Information

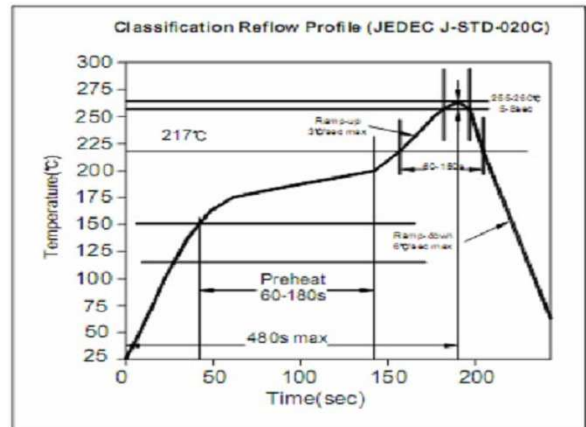
Serie and Range
S12004-3N9

Tolerance	ROHS	Packing
K	R	TR
J = 5%	R = ROHS	BU = Bulk Ware
K = 10%	N = non ROHS	TR = Tape Reel
M = 20%		
N = 30%		

**Soldering Profile for Lead Free Soldering
 235-240°C**



**Soldering Profile for Lead Free Soldering
 255-260°C**



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